

# MicroTCA Specification Development

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The 2024 MicroTCA/ATCA for Large Scientific Facility Control International Workshop  
University of Science and Technology of China (USTC), in Hefei, China



# SLAC & DESY Reliability Workshop 2005

## Challenges to operate huge facilities (e.g. ILC or Eu-XFEL) with thousands of devices

Example:

- Server PC has a MTBF ~50 000h (~99.99%)  
—> downtime per year: **53 minutes**
- With 1000 systems required to run it drops to 90%  
—> downtime per year: **37 days**

$$\text{Availability} = \text{MTBF} / (\text{MTBF} + \text{MTTR})$$

$$0.9999 = 50000 / (50000 + 5)$$

# Mean Time Between Failures

## MTBF Estimates for R1304RPMSHOR

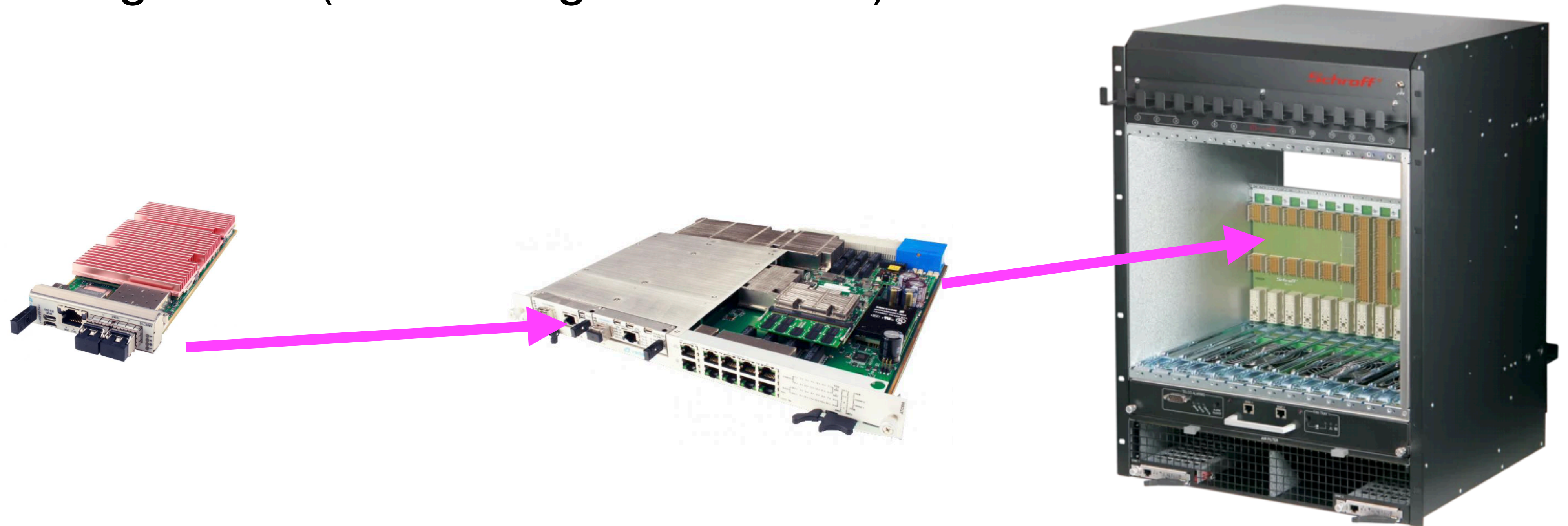
Copyright ©2013 Intel Corporation

| Subassembly<br>(Server in 40C ambient air) | Server Model  |                            |
|--|---------------|----------------------------|
|  | R1304RPMSHOR  |                            |
|  | MTBF          | FIT                        |
|  | (hours)       | (flrs/10 <sup>9</sup> hrs) |
| S1200V3RPM board                           | 371,523       | 2,692                      |
| Power Supply - 450W MiniERPS               | 967,300       | 1,034                      |
| Cooling Fan (1-fixed fans)                 | 490,000       | 2,041                      |
| Cooling Fan (2-fixed fans)                 | 77,680        | 12,873                     |
| Front Panel board                          | 8,272,282     | 121                        |
| HS Backplane(4x3.5")                       | 935,180       | 1,069                      |
| <b>Totals without motherboard =</b>        | <b>58,300</b> | <b>17,138</b>              |
| <b>Totals with motherboard =</b>           | <b>50,400</b> | <b>19,830</b>              |

MTBF  
is limited by the fan

# ATCA: a Standard Developed by Telecom Industry

- Introduced: 2003
- Requirements
  - 99.999% reliability —> downtime per year = 5.3 minutes
  - Very high system throughput (full mesh architecture)
  - Remote management (monitoring and control)



# MicroTCA: a Standard Developed by Telecom Industry

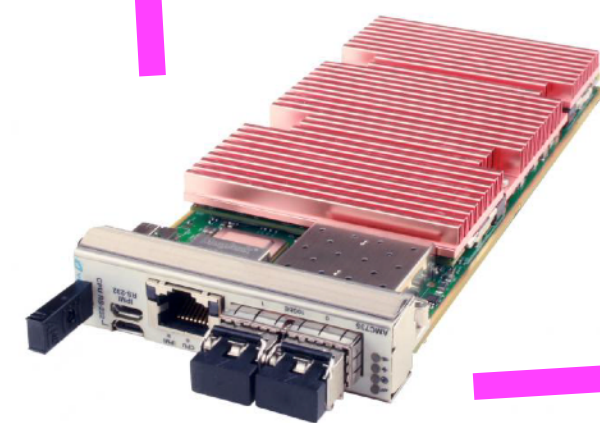
MicroTCA: 2006



ATCA: 2003



A scalable family with the same system architecture



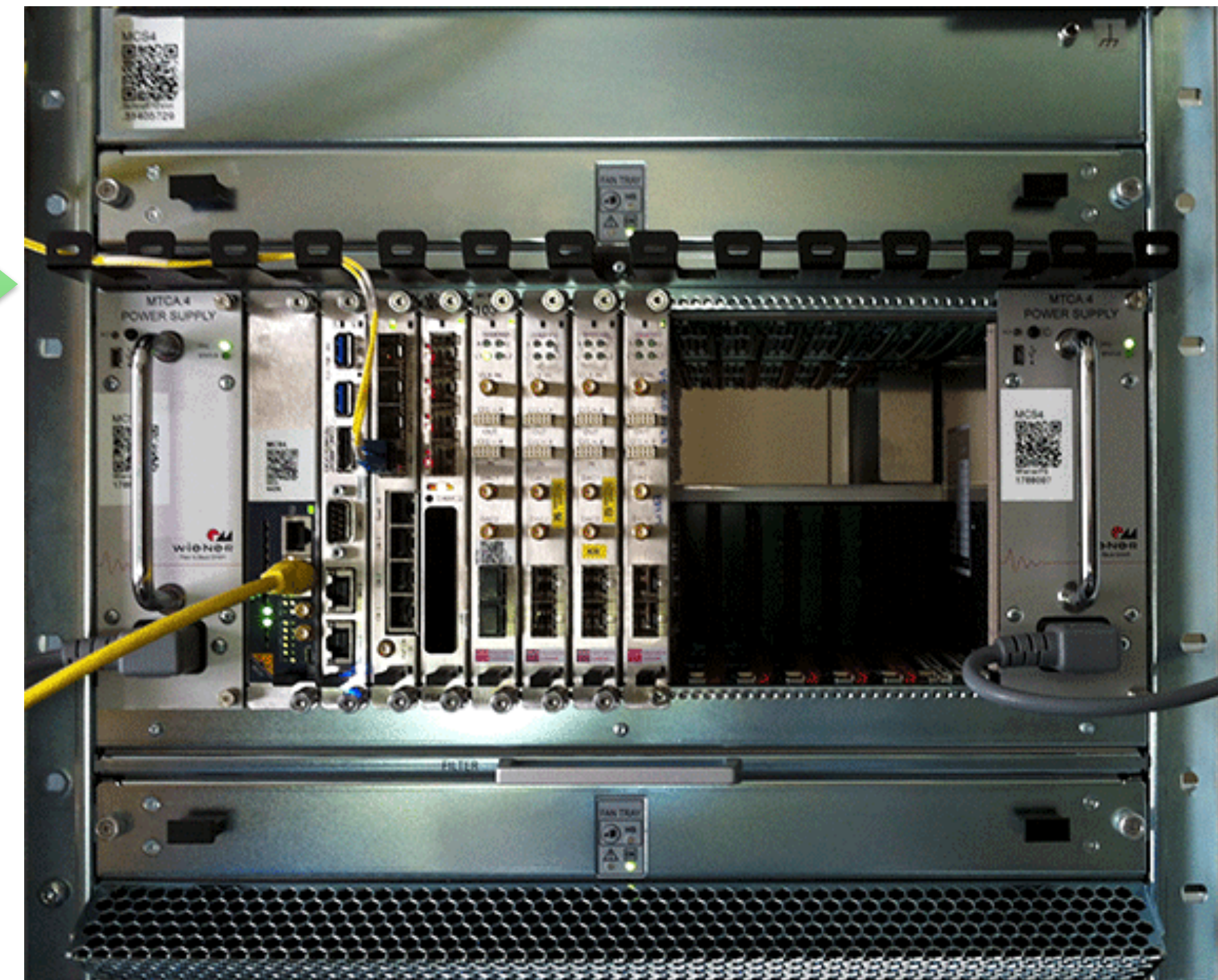
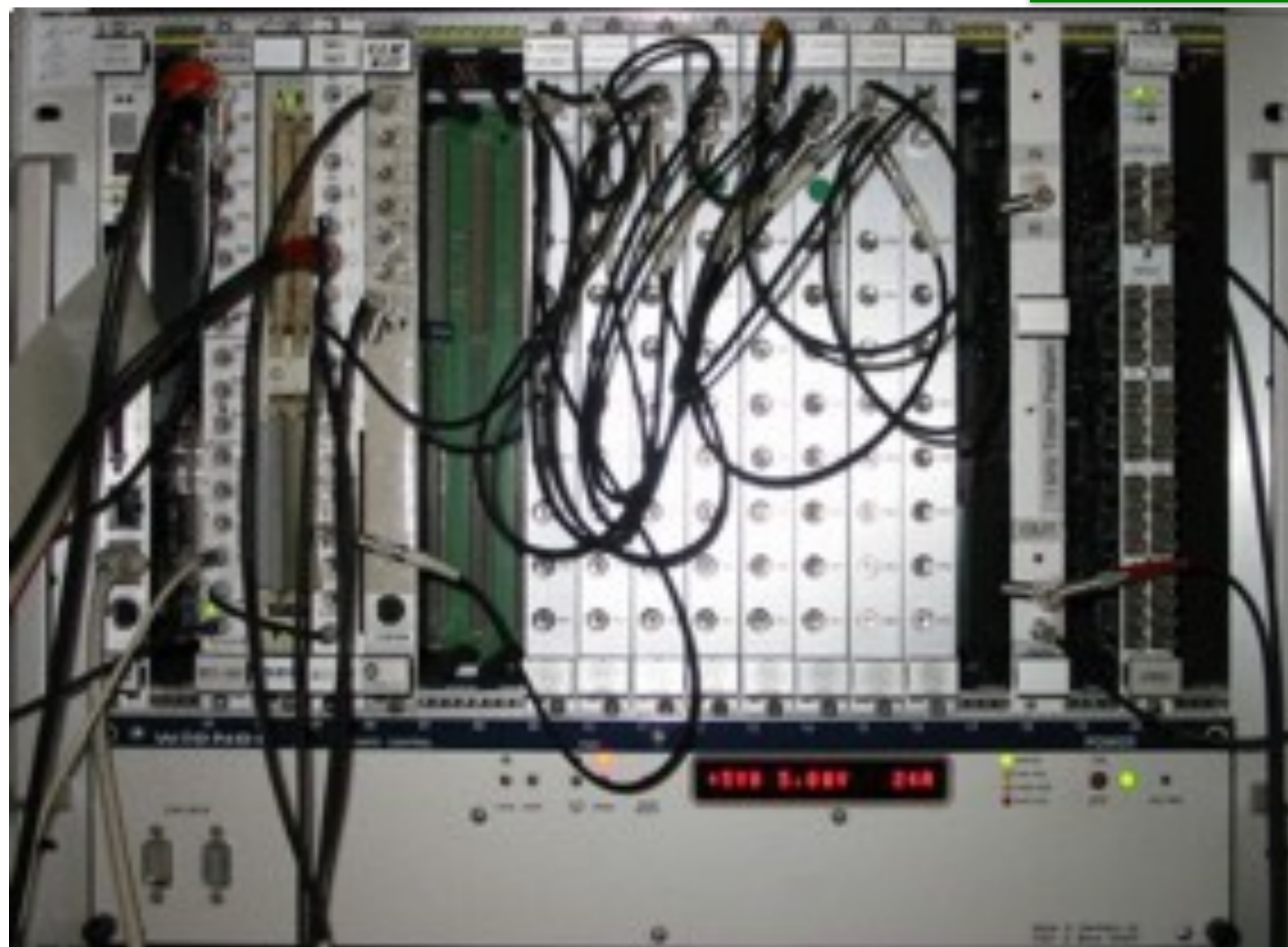
AMC



# VME → MicroTCA Migration @ DESY



- Since 1993 ... **VME** bus at FLASH

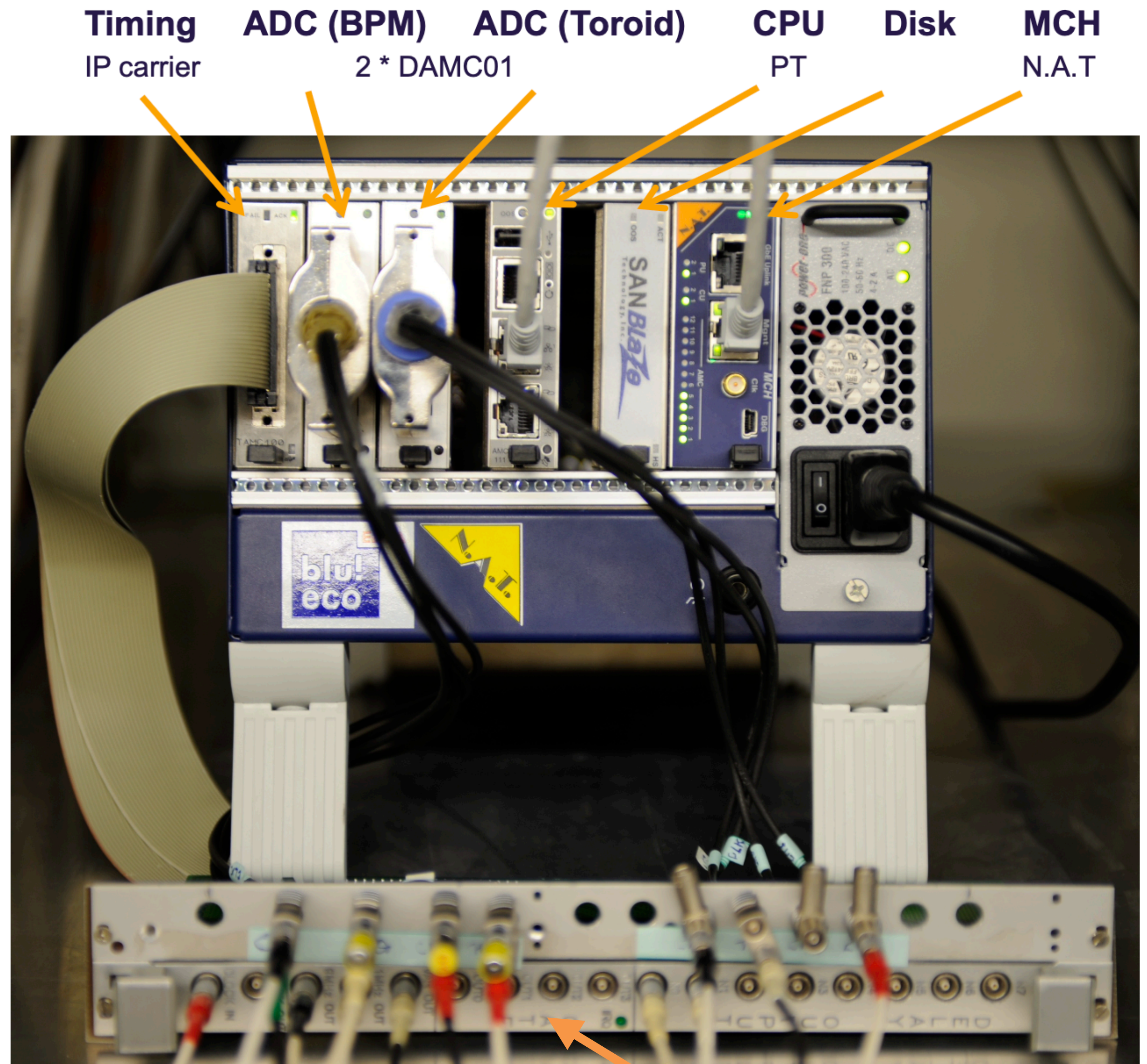


- Cables from rear
- Internal Clock & Trigger distribution
- Redundancy of fans
- Redundancy of power supplies possible
- Modern, high-speed Datentransfer
- Excellent signal quality for analog IO
- Remote management

# First Test System Running @ DESY 2009

## Used I/O modules:

- IP carrier to adapt the FLASH timing system
- Two channel ADC to read a Beam Position Monitor
- Two channel ADC to read the beam current



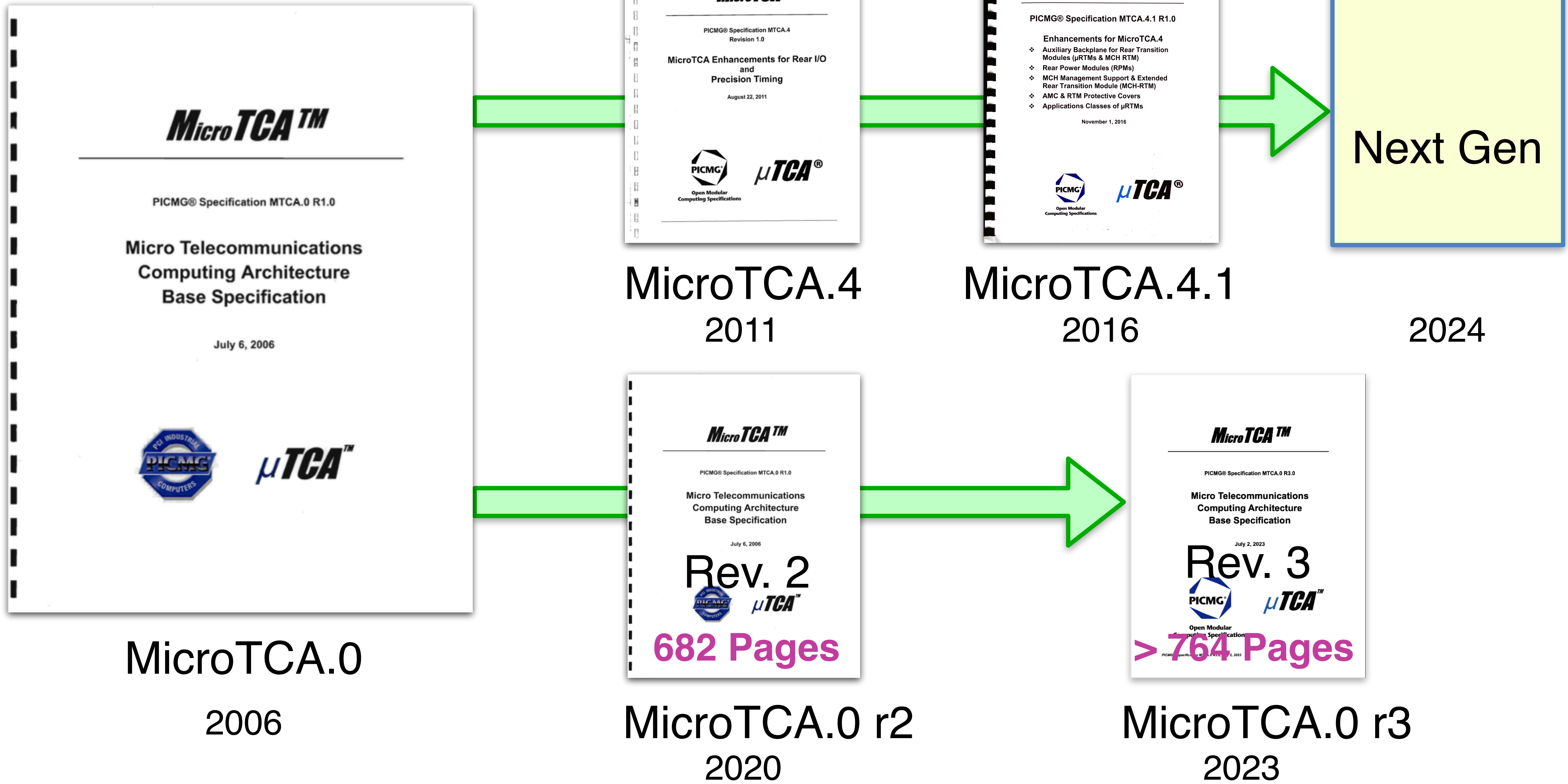
# Lessons Learned

- It all worked well
- But:
  - Not enough space on panels for cables
  - Not enough space for analog signal conditioning
  - Single size AMC is too small
  - Clock and trigger distribution should be inside crate
  - ...
- Conclusion: Start of MicroTCA.4 specification development **2009**



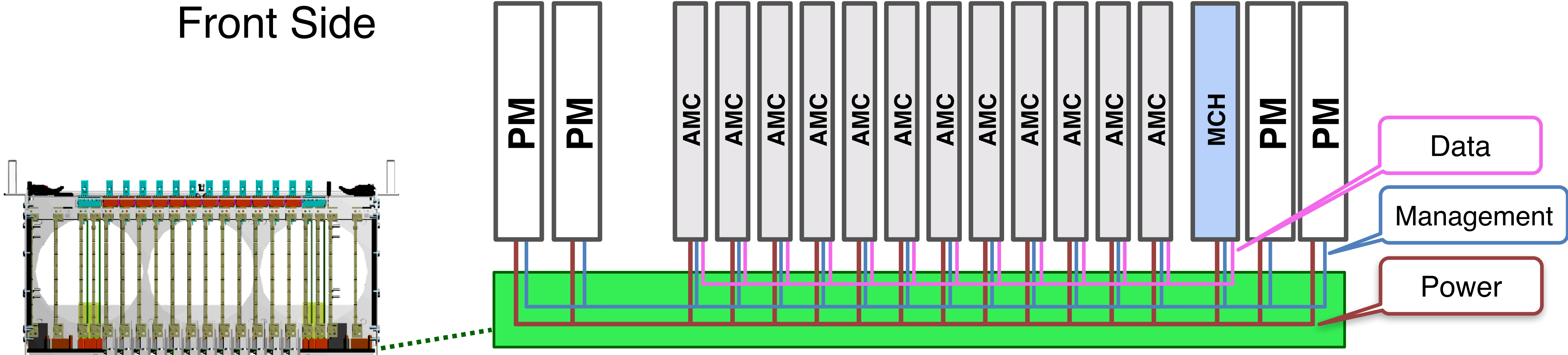


# MicroTCA Specifications

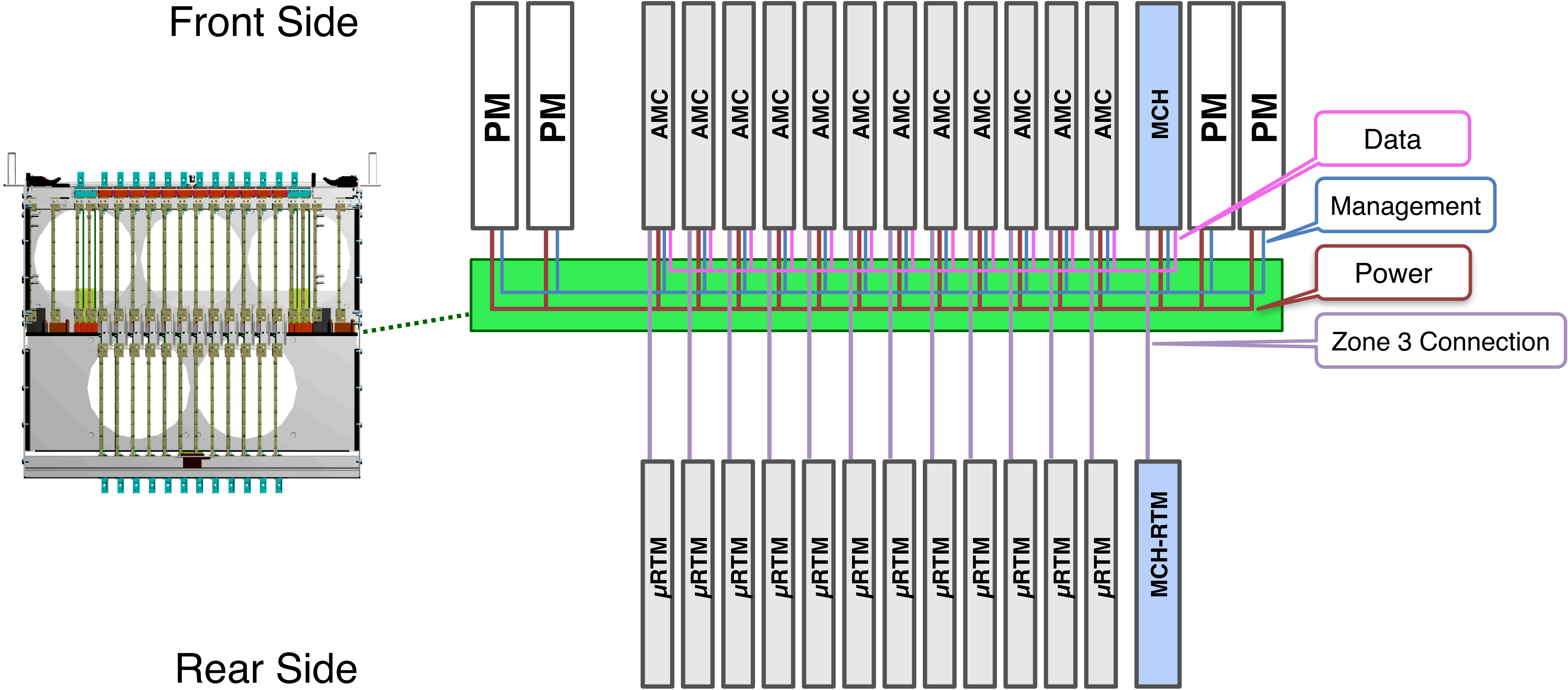


# MicroTCA Generations: **MTCA.0** MTCA.4 MTCA.4.1

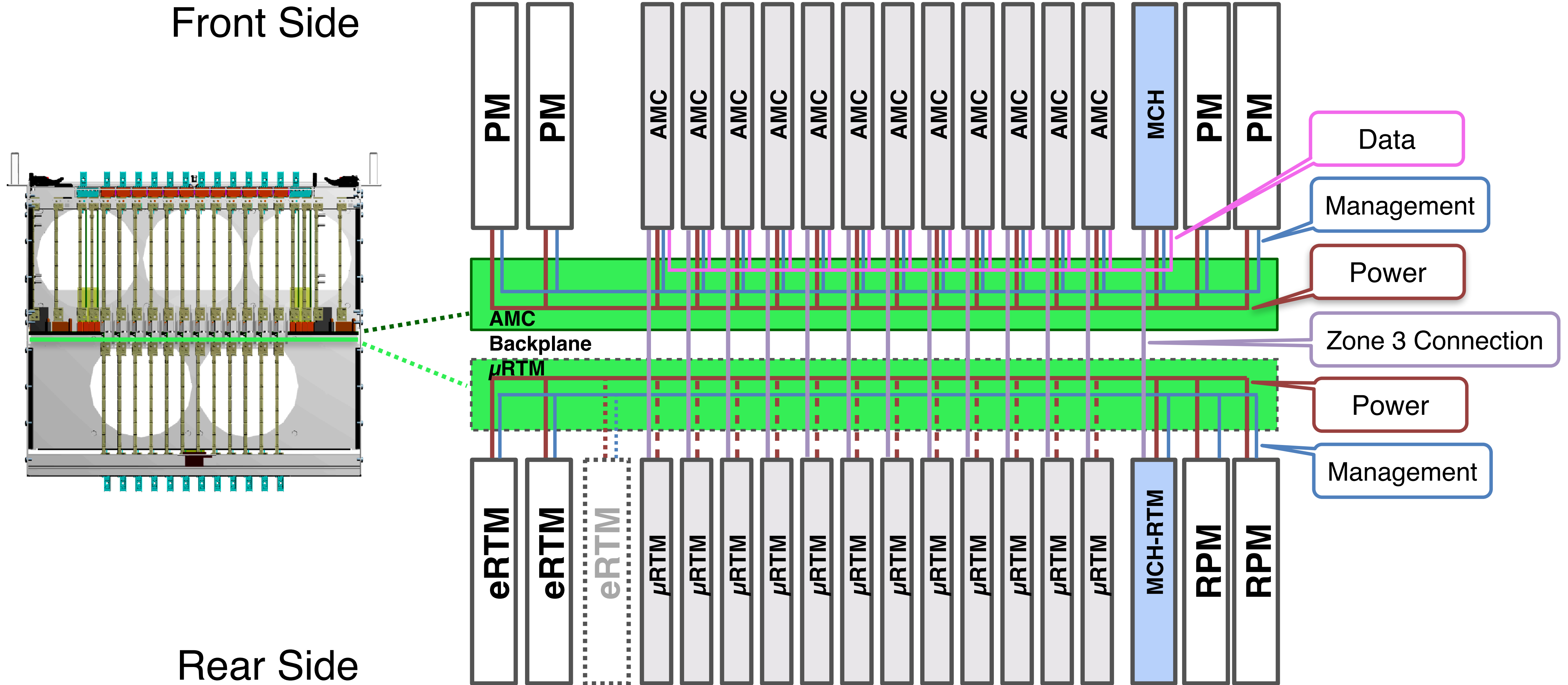
Front Side



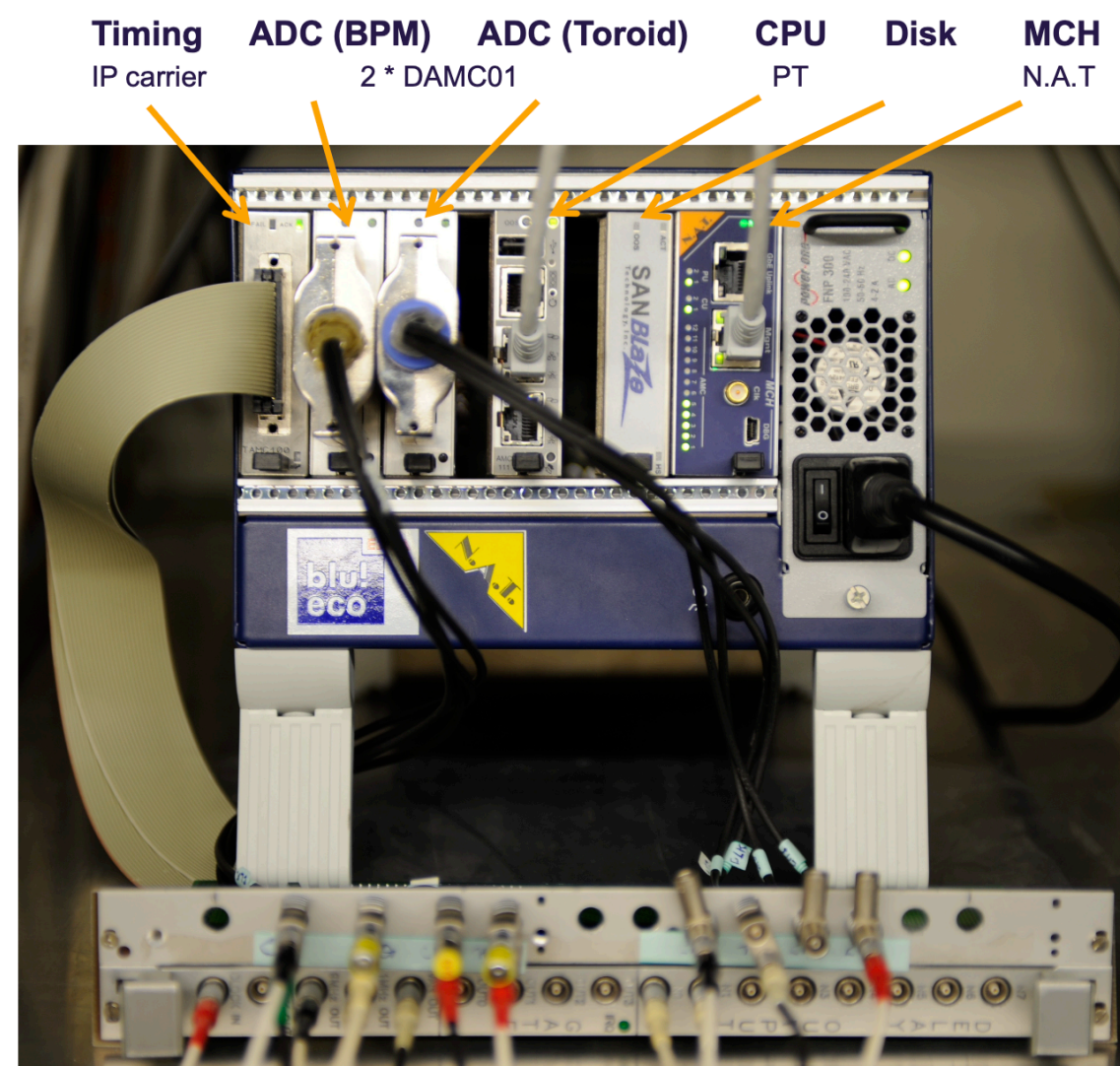
# MicroTCA Generations: MTCA.0 **MTCA.4** MTCA.4.1



# MicroTCA Generations: MTCA.0 MTCA.4 **MTCA.4.1**



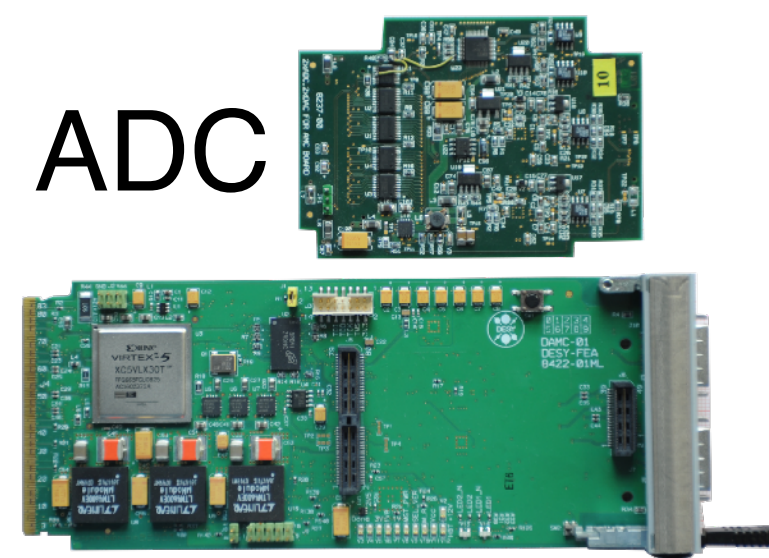
# MTCA.0 First Test 2009 → 2011 First LLRF MTCA.4



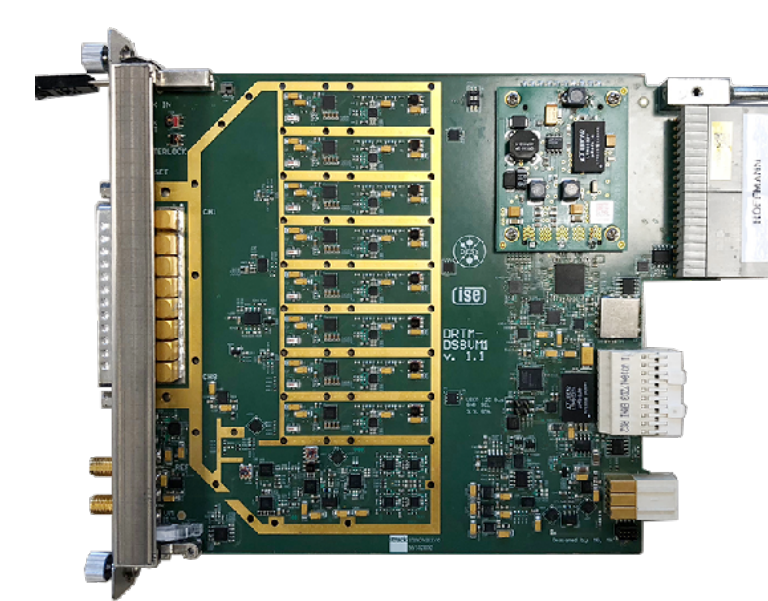
2009



2011



DESY DAMC1



Downconverter



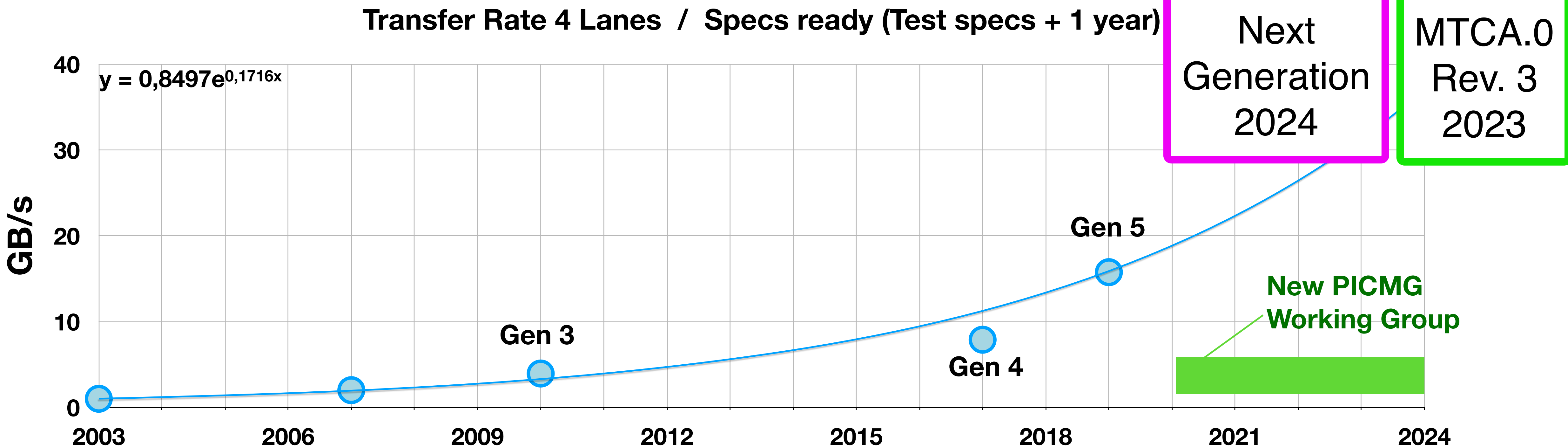
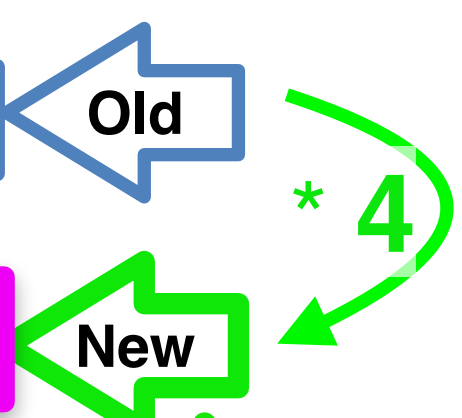
SIS8300

# Requirements for the Next Generation of MicroTCA

- **Keep the standard alive for a long time**
  - Adapt state-of-the-art technology
- **Backward compatibility**
  - All existing AMC modules **MUST** be usable
- **Protect your Investment**
  - Modularity: Just upgrade parts that limit your system

# Motivation: Technology Trends

| PCI Express version | Introduced     | Line code | Transfer rate | Throughput (simplex) |            |              |                        |           |
|---------------------|----------------|-----------|---------------|----------------------|------------|--------------|------------------------|-----------|
|                     |                |           |               | x1                   | x2         | x4           | x8                     | x16       |
| 1.0                 | 2003           |           | 2.5 GT/s      | 250 MB/s             | 0.50 GB/s  | 1.0 GB/s     | 2.0 GB/s               | 4.0 GB/s  |
| 2.0                 | 2007           | 8b/10b    | 5.0 GT/s      | 500 MB/s             | 1.0 GB/s   | 2.0 GB/s     | 4.0 GB/s               | 8.0 GB/s  |
| 3.0                 | 2010           |           | 8.0 GT/s      | 985 MB/s             | 1.97 GB/s  | 3.9 GB/s     | 7.88 GB/s              | 15.8 GB/s |
| 4.0                 | 2017           | 128b/130b | 16.0 GT/s     | 1969 MB/s            | 3.94 GB/s  | 7.9 GB/s     | 15.75 GB/s             | 31.5 GB/s |
| 5.0                 | 2019           | 128b/130b | 32.0 GT/s     | 3938 MB/s            | 7.88 GB/s  | 15.8 GB/s    | 31.51 GB/s   63.0 GB/s |           |
| 6.0                 | In preparation | PAM4      | 64.0 GT/s     | ~7800 MB/s           | ~15.7 GB/s | ~31.4.8 GB/s | ~62 GB/s               | ~124 GB/s |



# Technology Trends: CPU & FPGA

COM-HPC defines the direction of technology

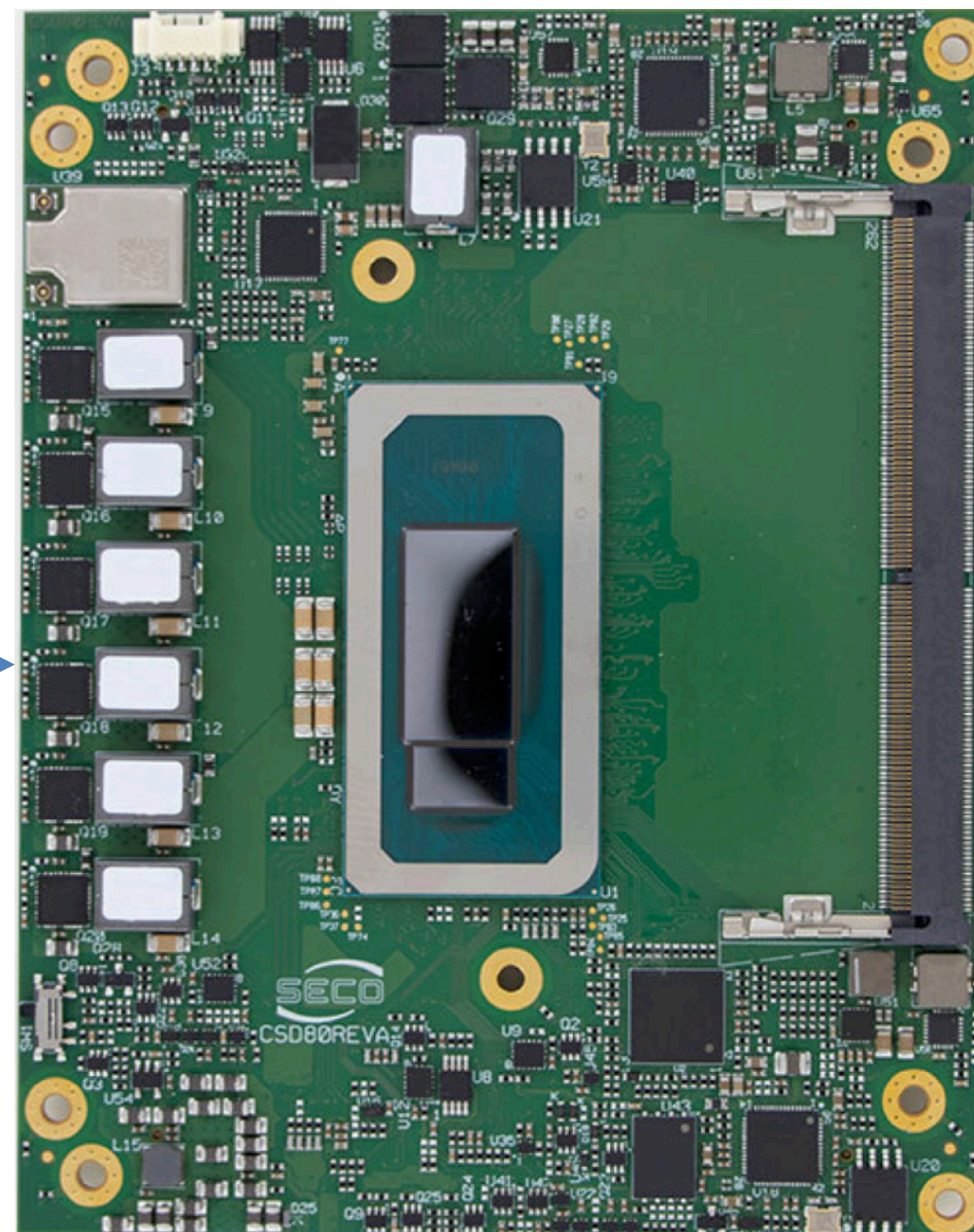
- Client type modules up to **200 Watt**
- Up to **49 PCIe gen 5 lanes**
- **PICMG** published 2021

Actual design:

- Intel 13th Gen: PCIe gen 4/5



COM+HPC®



© SECO

FPGA

- PCIe gen 4/5
- **75 ... 220 W**



© Xilinx® Alveo™



# PICMG MicroTCA Next Generation Working Group

Initial  
Executive  
Members  
... 14.11.2019

**ESS**  
**DESY**  
**Lodz University of Technology**  
**N.A.T.**  
**nVent**

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**Kay Rehlich, DESY**  
**Heiko Körte, N.A.T**  
**Thomas Holzapfel, powerBridge**

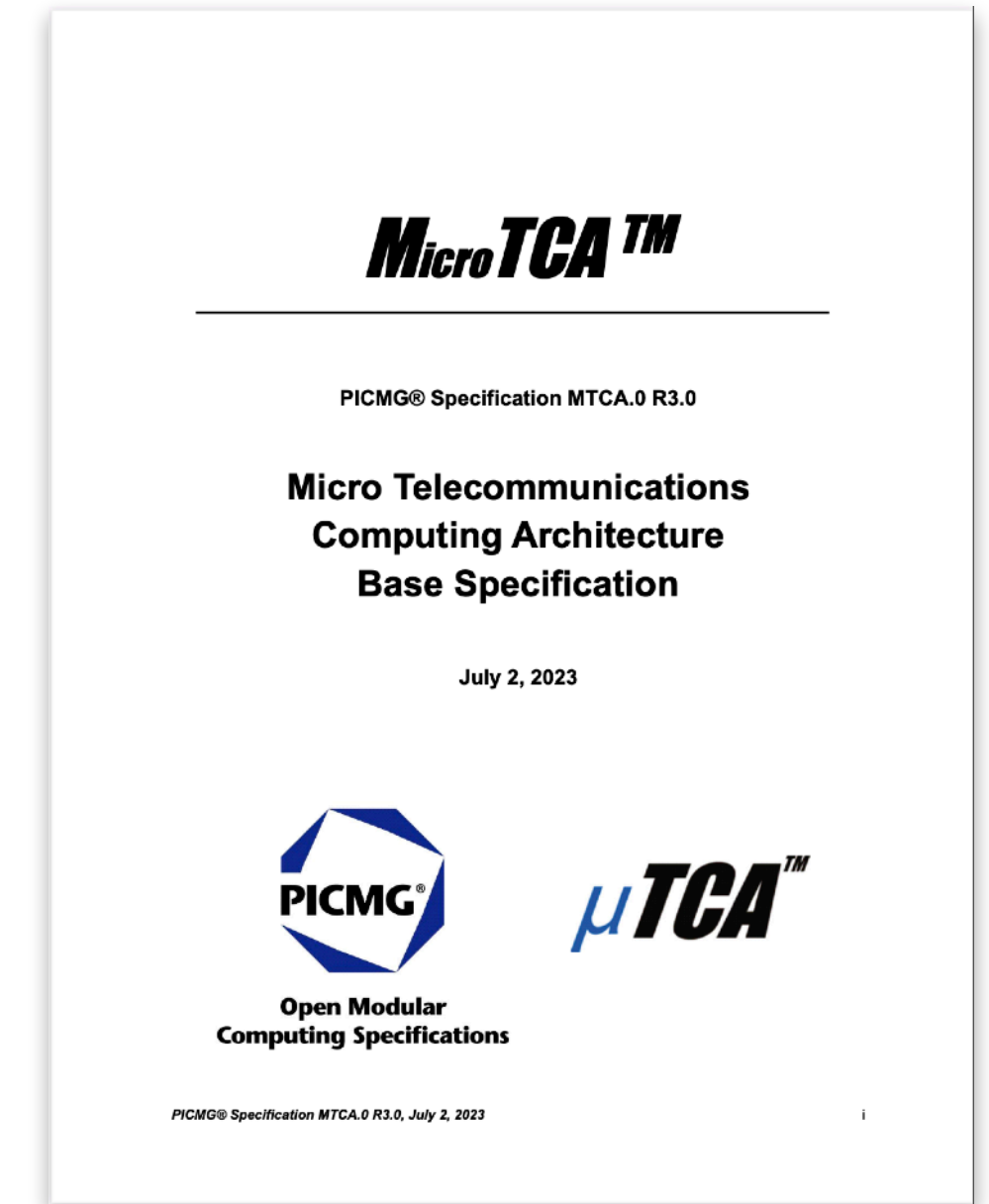
+ Members of  
working group

**Amphenol**  
**Atom Computing**  
**BAE Systems**  
**Comtel**  
**Concurrent Technologies**  
**Embeck**  
**IOxOS**  
**ORNL**  
**Pixus Technologies**  
**Positronic**  
**powerBridge**  
**Samtec**  
**VadaTech**  
**Yamaichi**



# MicroTCA Supports 32Gb/s Now

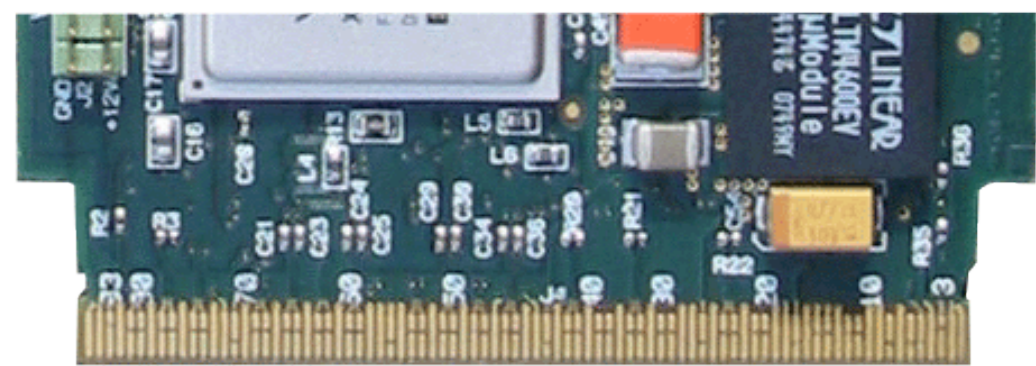
- **PCIe gen 5**
- **25GBASE-KR, 4 lanes: 100 G Ethernet**
- **110 W for MCH and cooling**



Rev. 3: July 2023

- **Next Step we are working on:**
  - Provide more PCIe lanes with **two connectors**
  - Allow up to **220 W per AMC (and MCH, cooling)**

# AMC Connector for: PCIe Gen 5 and More Power



✓ 32 Gb/s

**Old connector**

Possible new  
Connector  
**OPTIONAL!**

More  
Fat Pipe lanes  
e.g.  
PCIe x8, x16

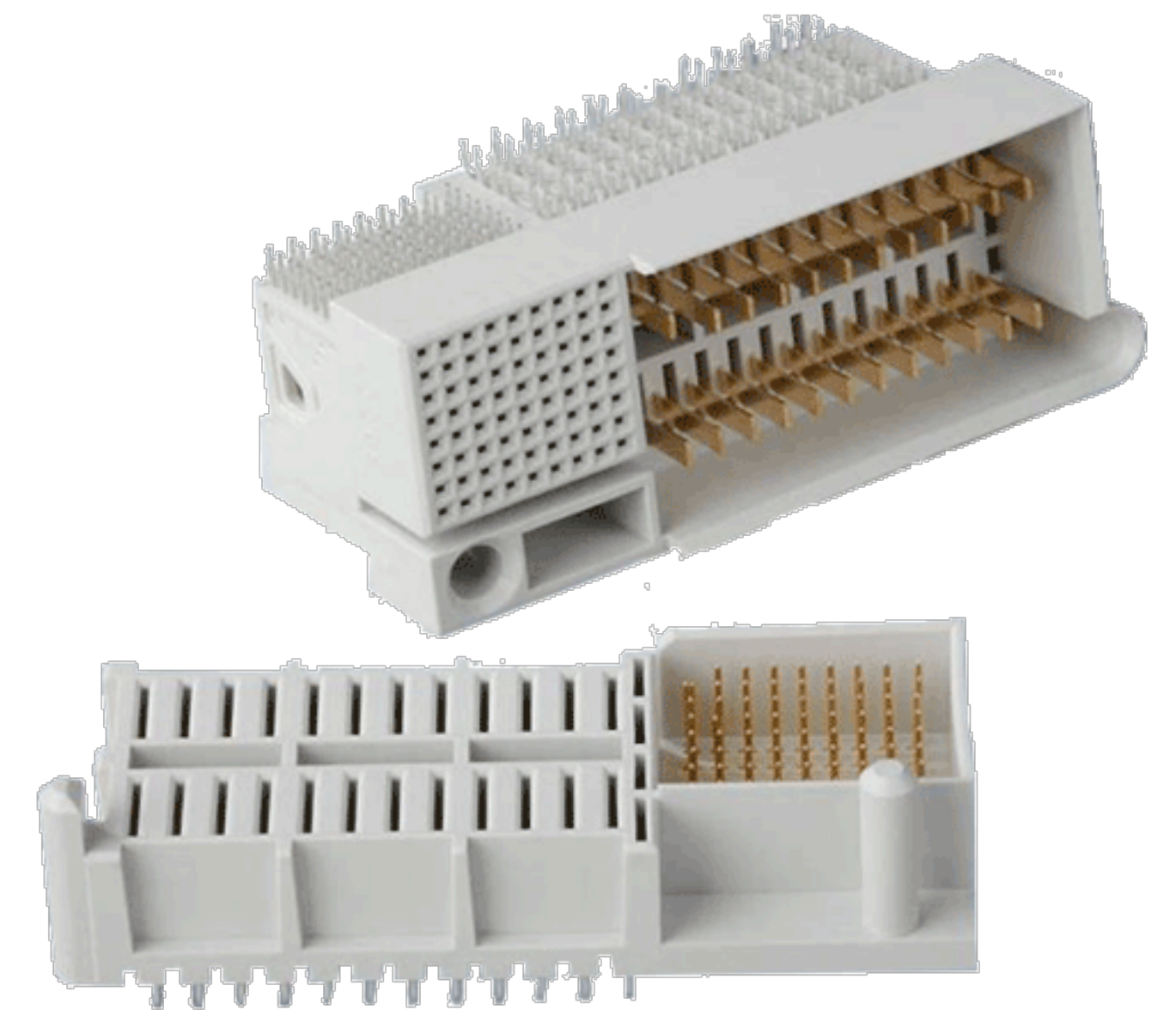
220 W:  
2 \* 9 power  
Pins

Card-edge  
Connector










**100% backward compatible**

# Challenges: Power

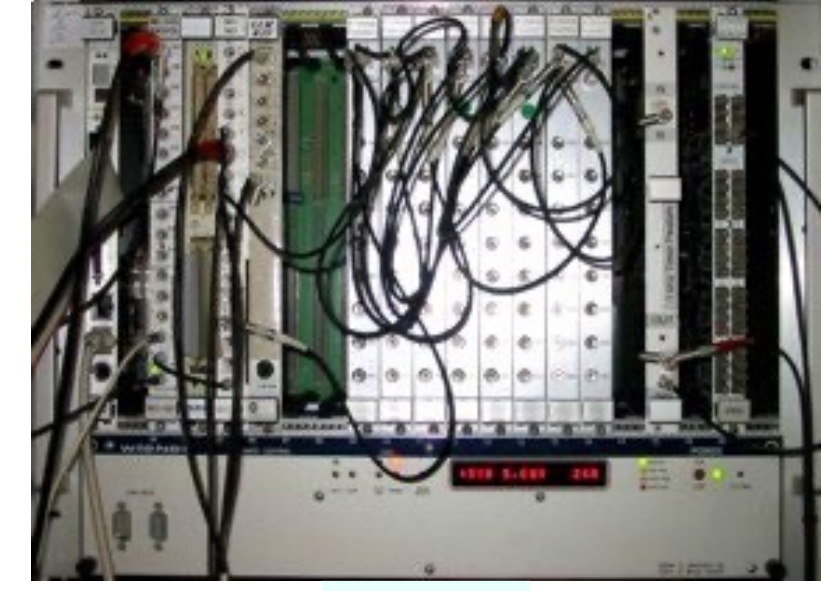
- **Increase power from 80 W → 220 W per slot**
  - Limitation of AMC connector: 8 pins @ 10.8 V = 98 W
  - Limitation of Power Module connector: 110 W
- **Solution:**
  - Use 9 pins on AMC + 2nd connector
  - Use 2 Power Module connectors
- **2 kW crate cooling**
  - Two times more airflow
  - Fans need more power
  - Simulations by nVent demonstrated the feasibility



# Summary

-  **ATCA started 2003:**  
Telecom system: high throughput, high reliability, remote management
-  **Reliability Workshop 2005**
-  **MicroTCA 2006:**  
Smaller, IO oriented systems with the same features as ATCA
-  **XFEL Decision to use ATCA or MicroTCA 2007**
-  **MicroTCA.4 2011:**  
Clock & Trigger integration  
RTM space for signal conditioning
-  **MicroTCA.4.1 2016:**  
2nd backplane for RTMs (e.g. for LLRF frequency distribution)
-  **XFEL Injector Dec. 2015, Main Linac 2017**
-  **MicroTCA 2023:**  
100 Gb Ethernet (~12 GB/s) and 15.8 GB/s PCIe gen 5
-  **MicroTCA Next Generation in preparation:**  
2 kW per crate, 220 W max. per AMC slot, 63 GB/s with 16 lanes

199x  
2003  
2005  
2006  
2007  
2011  
2016  
2017  
2023  
.  
.



VME

$\mu$ TCA<sup>®</sup>

